

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Serial No. : 10/526,383 Confirmation No. : 3829  
Filing Date : 13 September 2005 Art Unit : 1752  
First Named Inventor: Nobuji Sakai Examiner :  
Customer No. : 54884 Docket No. : Toyo-3  
Title: : Radiation-Sensitive Negative-Type Resist Composition for Pattern  
Formation and Pattern Formation Method

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**REQUEST FOR CORRECTION OF APPLICATION TITLE AND CORRECTED  
FILING RECEIPT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir or Madam:

The Applicant requests that the Title of the above-identified application be corrected as follows:

From: Radiation-Sensitive Negative-Type Resist Composition for Pattern  
Formation Method

To: Radiation-Sensitive Negative-Type Resist Composition for **Pattern  
Formation and** Pattern Formation Method

The application was a '371 filing from PCT Application No.: PCT/JP2003/011029. A copy of the publication page is attached hereto evidencing the title.

Upon correction of the title of the application, a Corrected Filing Receipt is respectfully solicited.

Respectfully submitted,  
GOMEZ INTERNATIONAL PATENT OFFICE, LLC

Dated: 2-13-2007

By:

  
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(43) International Publication Date  
18 March 2004 (18.03.2004)

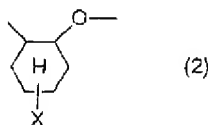
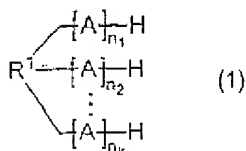
PCT

(10) International Publication Number  
**WO 2004/023213 A1**

- (51) International Patent Classification: G03F 7/038, 7/004
- (21) International Application Number: PCT/JP2003/011029
- (22) International Filing Date: 29 August 2003 (29.08.2003)
- (25) Filing Language: English
- (26) Publication Language: English
- (30) Priority Data: 2002-252926 30 August 2002 (30.08.2002) JP
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- (81) Designated States (national): CA, CN, KR, SG, US.
- (84) Designated States (regional): European patent (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PT, RO, SE, SI, SK, TR).
- Published:
- with international search report
- before the expiration of the time limit for amending the claims and to be republished in the event of receipt of amendments

[Continued on next page]

(54) Title: RADIATION-SENSITIVE NEGATIVE-TYPE RESIST COMPOSITION FOR PATTERN FORMATION AND PATTERN FORMATION METHOD



(57) **Abstract:** The radiation-sensitive negative type resist composition for pattern formation containing an epoxy resin, a radiation-sensitive cationic polymerization initiator, and a solvent for dissolving the epoxy resin therein, characterized in that the resist composition, through drying, forms a resist film having a softening point falling within a range of 30 to 120 C and that the epoxy resin is represented by formula (1): (wherein R1 represents a moiety derived from an organic compound having k active hydrogen atoms (k represents an integer of 1 to 100), each of  $n_1$ ,  $n_2$ , through  $n_k$  represents 0 or an integer of 1 to 100, the sum of  $n_1$ ,  $n_2$ , through  $n_k$  falls within a range of 1 to 100; and each of "A"s, which may be identical to or different from each other, represents an oxycyclohexane skeleton represented by formula (2): (wherein X represents any of groups represented by formulas (3) to (5): and at least two groups represented by formula (3) are contained in one molecule of the epoxy resin)).

